

HEXFRED® Ultrafast Soft Recovery Diode, 280 A



PRIMARY CHARACTERISTICS				
I _{F(AV)}	280 A			
V _R	600 V			
I _{F(DC)} at T _C	149 A at 100 °C			
Package	TO-244			
Circuit configuration	Two diodes common cathode			

FEATURES

- Very low Q_{rr} and t_{rr}
- UL approved file E222165





- · Designed and qualified for industrial level
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

BENEFITS

- · Reduced RFI and EMI
- · Reduced snubbing

DESCRIPTION / APPLICATIONS

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl_F/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	V _R		600	V	
Continuous forward current	I_	T _C = 25 °C	292		
Continuous forward current	I _F	T _C = 100 °C	149	Α	
Single pulse forward current	I _{FSM}	Limited by junction temperature 600			
Non-repetitive avalanche energy	E _{AS}	$L = 100 \mu H$, duty cycle limited by maximum T_J	2.2	mJ	
Maximum power dissipation P _D		$T_{C} = 25 ^{\circ}C$ 657		W	
		T _C = 100 °C	263	VV	
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	I _R = 100 μA		600	-	-	
		I _F = 105 A		-	1.33	1.8	V
Maximum forward voltage V _{FM}	I _F = 210 A	See fig. 1	-	1.53	2.1		
		I _F = 105 A, T _J = 125 °C		-	1.22	1.64	
Maximum reverse leakage current	I _{RM}	T _J = 125 °C, V _R = 600 V	See fig. 2	-	2.4	8	mA
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	280	400	pF
Series inductance	L _S	From top of terminal hole to mounting plane -		5.0	-	nΗ	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time		$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	39	-		
See fig. 5	t _{rr}	T _J = 25 °C	I _F = 105 A dI _F /dt = 200 A/μs	-	92	140	ns	
		T _J = 125 °C		-	180	270		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	9.3	17	Λ	
See fig. 6		T _J = 125 °C		-	16	30	A	
Reverse recovery charge	Q _{rr}	T _J = 25 °C	$V_{\rm R} = 200 \text{ V}$	-	490	1200	nC	
See fig. 7		T _J = 125 °C		-	1400	4000	IIC IIC	
Peak rate of recovery current	Peak rate of recovery current	all /alt	T _J = 25 °C		-	290	-	A/µs
See fig. 8	dI _{(rec)M} /dt	T _J = 125 °C		-	200	-	AvμS	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range		T _J , T _{Stg}	-55	-	150	°C	
Thermal resistance, junction to case	per leg	В	-	-	0.19	°C/W K/W	
	per module	R _{thJC}	-	-	0.095		
Typical thermal resistance, case to heatsink		R _{thCS}	-	0.10	-	1011	
Walaht			-	68	-	g	
Weight			-	2.4	-	oz.	
Mounting torque (1)			30 (3.4)	-	40 (4.6)		
Mounting torque (1)	center hole		12 (1.4)	-	18 (2.1)	lbf · in (N · m)	
Terminal torque			30 (3.4)	-	40 (4.6)	(14 111)	
Vertical pull			-	-	80	lbf ⋅ in	
2" lever pull			-	-	35	IDI · III	

Note

⁽¹⁾ Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached.

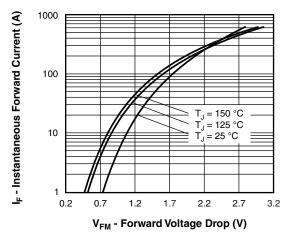


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

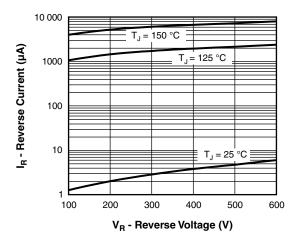


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

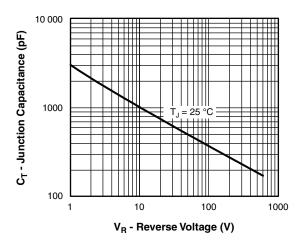


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

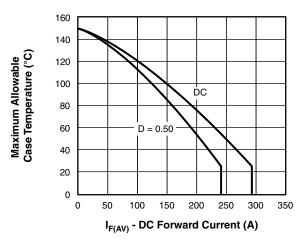


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

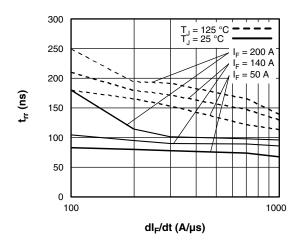


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt (Per Leg)

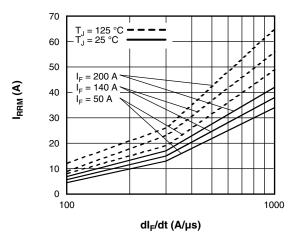


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

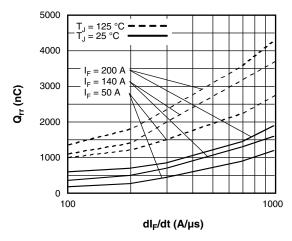


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

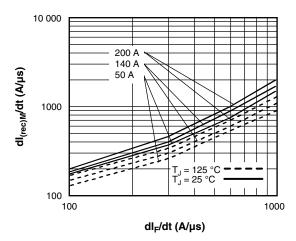


Fig. 8 - Typical dl_{(rec)M}/dt vs. dl_F/dt (Per Leg)

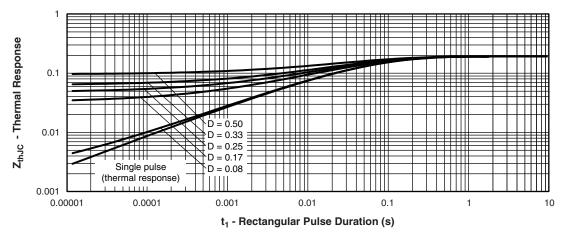


Fig. 9 - Maximum Thermal Impedance ZthJC Characteristics (Per Leg)

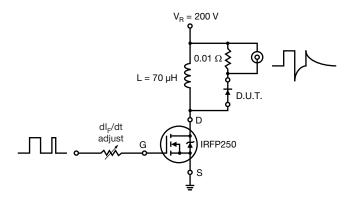
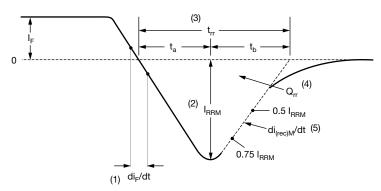


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions



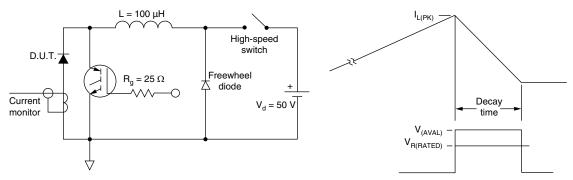


Fig. 12 - Avalanche Test Circuit and Waveforms

ORDERING INFORMATION TABLE

Device code



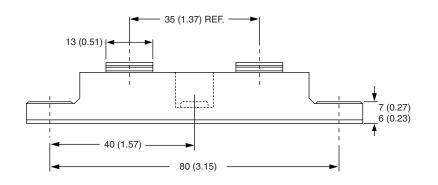
- 1 Vishay Semiconductors product
- 2 HEXFRED® family, electron irradiated
- 3 Average current rating
- **4** NJ = TO-224
- 5 Voltage rating (600 V)
- 6 C = two diodes common cathode
- 7 Lead (Pb)-free

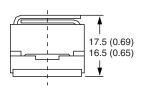
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95021			

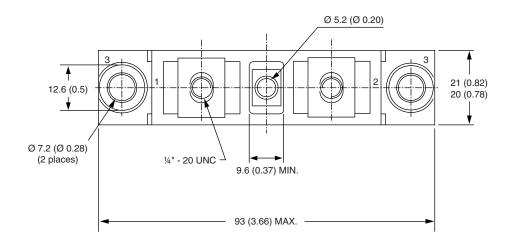


TO-244

DIMENSIONS in millimeters (inches)









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